Tangram: Integrated Control of Heterogeneous Computers

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Heterogeneous Systems



Nvidia GPU

Discrete integration (Image courtesy: NVIDIA)



Heterogeneous Systems



Discrete integration (Image courtesy: NVIDIA)



On-package integration



Heterogeneous Systems



Challenge: System-wide efficiency with distributed resource control



Run as firmware on embedded microcontrollers



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Limitation I: Many heuristic algorithms Conflicting, and hard to reuse



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Limitation 2: Centralized control



Slow, ineffective because of non-modularity. Hard to reuse.



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Why is the state of the art so limited?



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Why is the state of the art so limited? I. Distributed control is difficult 2. Heuristics appear intuitive



Contributions

 Tangram: a distributed control framework that is modular, fast, and globally coordinated



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• A novel controller design that uses formal control, and with a standard interface



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• A novel controller design that uses formal control, and with a standard interface

• Prototype on a multi-vendor heterogeneous server



Classifying Resource Control Goals

Safety

thermals, voltage droops

Immediate response for protection



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Immediate response for protection

Enhancement

minimize Energy×Delay

Requires search



Classifying Resource Control Goals

Safety

thermals, voltage droops

Preconfigured

optimal for common patterns

Enhancement

minimize Energy×Delay

Immediate response for protection

Immediate response for optimality Requires search















Targets























Formal, coordinated optimization replaces piecemeal heuristics









Matrices [A, B, C, D], and state





Matrices [A, B, C, D], and state

inputs = $\mathbf{C} \times \text{state} + \mathbf{D} \times \text{deviations}$





Matrices [A, B, C, D], and *state*

inputs = $\mathbf{C} \times \text{state} + \mathbf{D} \times \text{deviations}$ state_{new} = $\mathbf{A} \times \text{state} + \mathbf{B} \times \text{deviations}$





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inputs = $\mathbf{C} \times \text{state} + \mathbf{D} \times \text{deviations}$ state_{new} = $\mathbf{A} \times \text{state} + \mathbf{B} \times \text{deviations}$ Every T time-units





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state_{new} = $\mathbf{A} \times \text{state} + \mathbf{B} \times \text{deviations}$ Every T time-units

Deviations are small even when runtime conditions differ from design conditions


















































Subsystem, e.g., CPU Chip





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Optimize/control locally and propagate constraints hierarchically



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Control organization naturally fits the hierarchical organization of the computer





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- Fast
- Globally coordinated



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- Modular



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Obvious and simple: Thanks to formal control!



Prototype



CPUs: AMD Ryzen™ 1800X GPU: AMD Radeon™ RX 580

Controllers built as privileged processes



Prototype





CPUs: AMD Ryzen[™] 1800X GPU: AMD Radeon[™] RX 580

Controllers built as privileged processes



Prototype



Minimize Energy×Delay with power constraints Current and temperature safety



CPUs: AMD Ryzen[™] 1800X GPU: AMD Radeon[™] RX 580

Controllers built as privileged processes









Centralized





Centralized

Always 200 ms









Centralized

Always 200 ms





Common case: 15 ms Worst case: 515 ms



Centralized Tangram CPU C C C Chip I Always 200 ms Common case: 15 ms Worst case: 515 ms CPU С Chip 2 Preconfigured and Safety response is $\approx 2 \text{ ms}$ **CPU** Cluster С **GPU** Chip Node



Control frameworks

- Research state-of-the-art
- Tangram with heuristic
- Tangram



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Chai applications

Fine grained concurrent CPU-GPU execution



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Normalized Energy x Delay 1.2 0.91 0.8 0.59 0.6 0.4 0.2 0 Research state- Tangram with Tangram of-the-art heuristic



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Tangram: 32% faster with 13% lower energy \Rightarrow 41% better EDP



Collaborative Application: rsct from Chai

Research state-of-the-art

Tangram



Collaborative Application: rsct from Chai




Collaborative Application: rsct from Chai





Collaborative Application: rsct from Chai



Fine-grained power re-assignment





- Heterogeneous hardware is ubiquitous
 - Need to rethink resource control for efficiency and safety



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Also in the paper:

- Resource control from leading chip-makers Detailed design of Tangram
- Prototype implementation
- Complete evaluation



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